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PN - JP6168845 A 19940614
PD - 1994-06-14
PR - JP19920345477 19921130
OPD - 1992-11-30
TI - CHIP TYPE LAMINATED FILM CAPACITOR
IN - ENDO KAZUYOSHI
PA - MARCON ELECTRONICS CO
IC - H01G4/30 ; H01G1/147 ; H01G4/24 ; H05K3/34

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TI - Method of mfg. an electrolytic capacitor - comprises using two sets of metallic layers connected together to form terminals followed by coating with conductive adhesive and solder plating.

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PA - (MARJ) MARCON ELECTRONICS CO LTD

IC - H01G1/147 ; H01G4/24 ; H01G4/30 ; H05K3/34

AB - J06168845 In this method the capacitor is formed with metallic and plastic layers as conductors and dielectrics respectively. The metallic layers (4) are divided into two sets. Layers of one set are connected together by another metallic layer (5) at one end to form one terminal of capacitor. The same exercise is done to the other set where a metallic layer (6) forms the other terminal. To each of these faces an adhesive conductor (8) is applied and after that solder plating is done.

- ADVANTAGE - Improved external electrode structure. Easy for soldering and allows ease of miniaturisation without effecting electrical properties.

- (Dwg.1/4)

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TI - CHIP TYPE LAMINATED FILM CAPACITOR

- AB - PURPOSE: To provide a chip type laminated film capacitor having a small change with time and a good solderability without reducing electrical characteristics.
- CONSTITUTION: A plurality of metallized plastic films 3 are laminated between protective film layers 1 and 2 serving as the outside, and conductive adhesive layers 8 are formed on metallized layers 5 and 6 of a capacitor element 7 in which the metallized layers 5 and 6 are formed on both the ends to which deposited electrode parts 4 of the metallized plastic films 3 are alternately led out, and solder plating layers 9 are formed on the conductive adhesive layers 8.

SI - H05K3/34

I - H01G4/30 ; H01G1/147 ; H01G4/24